



Product Change Notification / JAON-03UTRS739

Date:

09-Mar-2015

Product Category:

8-bit Microcontrollers, Analog to Digital Converters, Digital Potentiometers, Interface- Controller Area Network (CAN), Interface- Infrared Products, Interface- Passive-Keyless-Entry Analog Front End, KEELOQ® Encoder Devices, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Touch Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 1155.38 Final Notice: Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 120K and 121K wafer technologies available in 14L SOIC package

Notification Text:

PCN Status: Final notification

Microchip Parts Affected: See attachments of affected catalog part numbers (CPN) labeled as...PCN_JAON-03UTRS739_Affected_CPN.xlsPCN_JAON-03UTRS739_Affected_CPN.pdf

Description of Change: Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 120K and 121K wafer technologies available in 14L SOIC package at MTAI assembly site.

NOTE: Selected products are non-automotive devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change: Gold wire and 8390A die attach epoxy

Post Change: PdCu wire and 3280 die attach epoxy or Gold wire and 8390A die attach epoxy.

Impacts to Data Sheet: None

Reason for Change:To improve manufacturability and qualify PdCu bond wire at MTAI assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:March 23, 2015 (date code: 1513)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History:**October 31, 2014:** Issued initial notification using the Notification ID JAON-15PAQT740.**March 06, 2015:** Issued final notification using the Notification ID JAON-03UTRS739. Revised the subject and description to only include the qualification of 120K and 121K wafer technology. Added the qualification of 3280 die attach epoxy on the subject and description. Attached the qualification report. Revised the estimated first ship date from December 19, 2014 to March 23, 2015.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-03UTRS739_Qual_Report.pdf](#)
[PCN_JAON-03UTRS739_Affected CPN.pdf](#)
[PCN_JAON-03UTRS739_Affected CPN.xls](#)

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